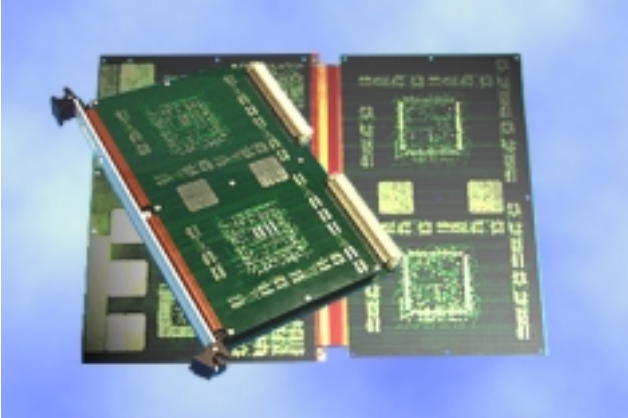




TELEDYNE
ELECTRONIC TECHNOLOGIES
Printed Circuit Technology
A Teledyne Technologies Company



Introducing VME Flex™

High Density Rigid Flex for COTS / VME Applications

Teledyne Electronic Technologies (TET) has developed a novel substrate for high density VME 6U applications. VME Flex™ is a standardized form factor to replace more traditional hard board solutions to improve performance and reliability while reducing overall system costs. Because the form factor is standard, the basic engineering tools have been established and the mechanical performance has already been qualified. Customer-supplied netlists, Bill of Materials, and component footprints are all that are needed to complete the design. This drastically reduces turnaround and qualification schedules.

Based on Teledyne's REGAL Flex[®] technology, VME Flex™ can be folded into the VME chassis envelope without the need for daughter cards, associated connectors, and other interconnect hardware. Both electrical and thermal performance are enhanced as a result. Re-

strictions based upon connector I/O density are essentially eliminated. The elimination of solder interconnects reduces assembly time and cost and increases product reliability. Design engineers can incorporate more functionality into the same overall space using this unique technology. Finally, because this is an "open" standard, sole sourcing issues are nonexistent.

Increasing Interconnect Density

The materials and processes used to produce these multilayer rigid flex products are similar to those currently used to manufacture circuit boards for military and aerospace applications. The core of the construction is Teledyne's patented REGAL Flex[®] construction that offers the highest thermal and dimensional stability of any rigid flex substrate. VME Flex™ can also be built with nonproprietary adhesiveless laminate constructions. This, coupled with advanced assembly techniques, such as, flip chip and chip-on-board, significantly increases interconnect density for the end user.

Teledyne is proud to offer design, fabrication and assembly services for the shortest time to market. ■

TYPICAL PRODUCT HIGHLIGHTS

REGAL Flex[®] multilayer rigid flex substrates:

- Ensure dimensional stability
- Provide greater packaging density while reducing weight, assembly complexity and cost
- Provide better electrical and thermal performance

VME Flex™ form factor compatible with 6U chassis:

- Major design, engineering operations, and tooling are already complete
- Available in adhesiveless laminate and REGAL Flex[®] constructions
- Provide better electrical and thermal performance

PHYSICAL DATA

- Feature size: 0.005" typical, 0.004" available
- Blind, buried, and micro vias available
- Direct attach of bare die (6 mil pitch wire bond)

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